

Reverse Bias - Junction C dominates
Reactance.

Forward Bias - Charge Storage c dominates.

Here, have I and E so some charge Q
across junction. But V lags I .

→ Due to stored charge.

Stored charge is injected hole distribution.

S&B Figure 5-16(b)

So C_s directly proportional to Q_p

Note: $\frac{q}{kT} = \frac{\text{charge}}{\text{energy}} = \frac{\text{charge}}{\text{charge-voltage}} = \frac{1}{\text{Voltage}}$

So $C_s \propto \frac{Q}{\text{Voltage}}$ analogous form as parallel plate capacitor

$$\tau = \frac{Q_p}{I_p} = \frac{\text{stored charge}}{\text{characteristic time to replenish recombining charge}}$$

$$C_s =$$

so C_s directly proportional to τ_p

(Need to reduce for high- ω circuits)

$$D/L = L/\tau \text{ since } L^2 = D \tau$$

Now can get AC conductance.

$$G_s = \frac{dI}{dV} = \frac{d}{dV} \left(g A L_p P_n e^{qV/kT} \right)$$

$$= g^2 A L_p P_n e^{qV/kT}$$

$$= g \frac{Q_p}{kT} = \frac{g}{kT} I = \frac{C_s}{\tau_p}$$

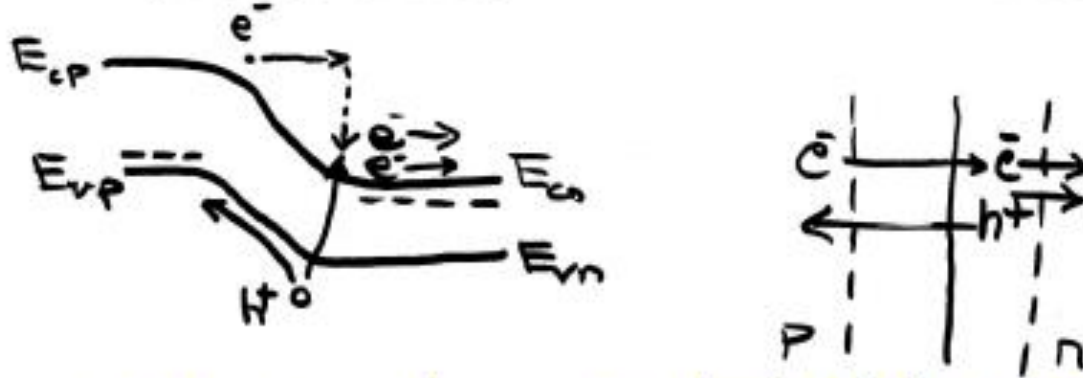
$$\begin{aligned} C_s &= \frac{g}{kT} I \tau_p \\ \frac{dC_s}{dt} &= \frac{g}{kT} I \frac{d\tau_p}{dt} \\ &= G_s \end{aligned}$$

$$i_{AC} = \frac{dQ}{dt} = \frac{d}{dt} (C_s V_{a-c}) = \frac{dC_s}{dt} V_{a-c} + C_s \frac{dV_{a-c}}{dt}$$

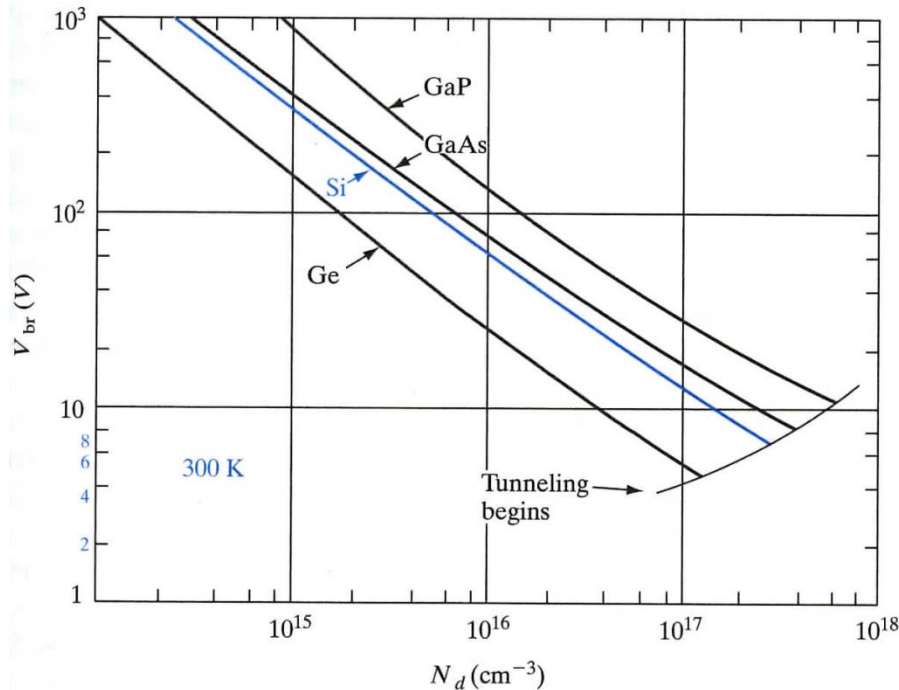
$$= G_s V_{a-c} + G_s \tau_p \frac{dV_{a-c}}{dt}$$

Reduce τ_p to improve a-c response.

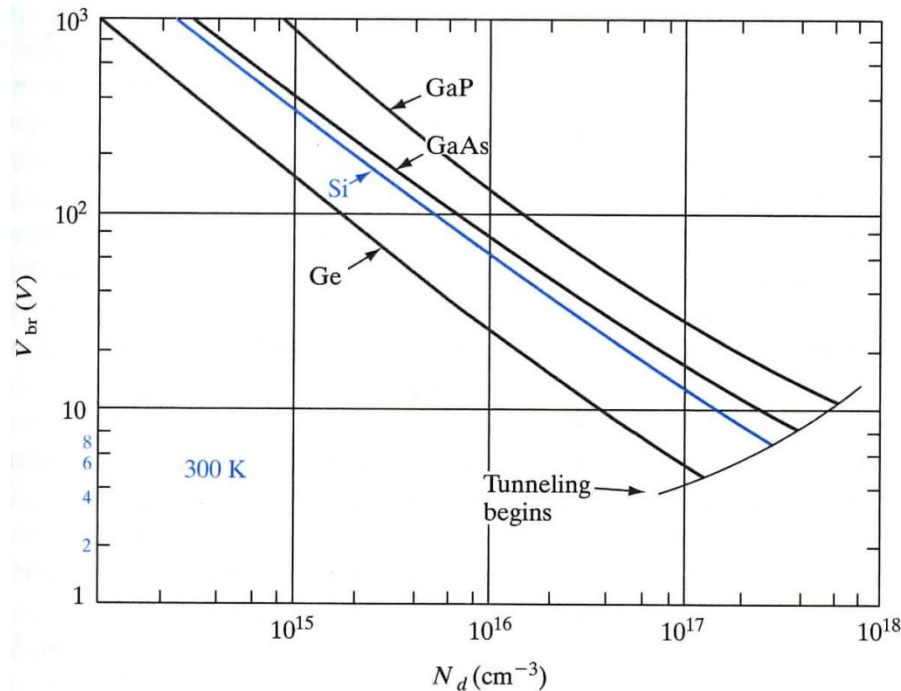
P-N Junction: Avalanche Breakdown



Electron's extra kinetic energy creates electron-hole pairs



S&B Figure 5-22



Breakdown Voltage V_{br} increases
with and decreases

with

Tunneling:



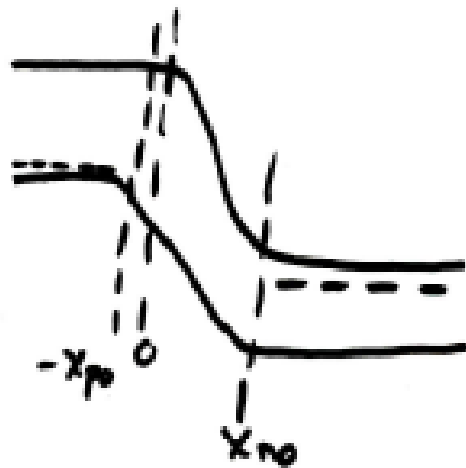
very
narrow

Critical Field at Breakdown

Consider pt-n "one-sided" junction

$$x_{n0} \gg x_{p0}$$

$$W = x_{n0} + x_{p0} \sim x_{n0}$$



$$\max E = -q \frac{N_d}{\epsilon} x_{n0}$$

$$x_{n0} = \frac{W N_a}{N_a + N_d} = \frac{\epsilon}{N_a + N_d} \left[\frac{2\epsilon V_0}{q} \left(\frac{1}{N_a} + \frac{1}{N_d} \right) \right]^{1/2}$$

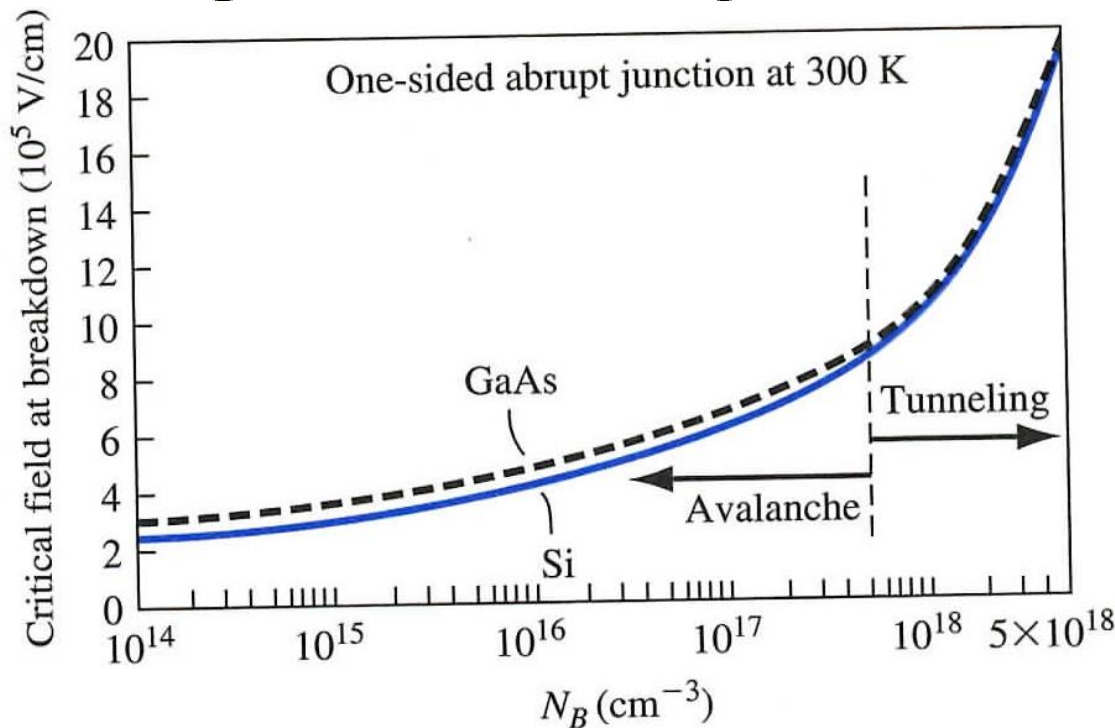
$$\text{For } N_a \gg N_d, \quad x_{n0} = \left[\frac{2\epsilon V_0}{q N_d} \right]^{1/2}$$

For reverse bias

$$X_{no} = \left[\frac{2\epsilon (V_0 + V_r)}{q N_d} \right]^{1/2}$$

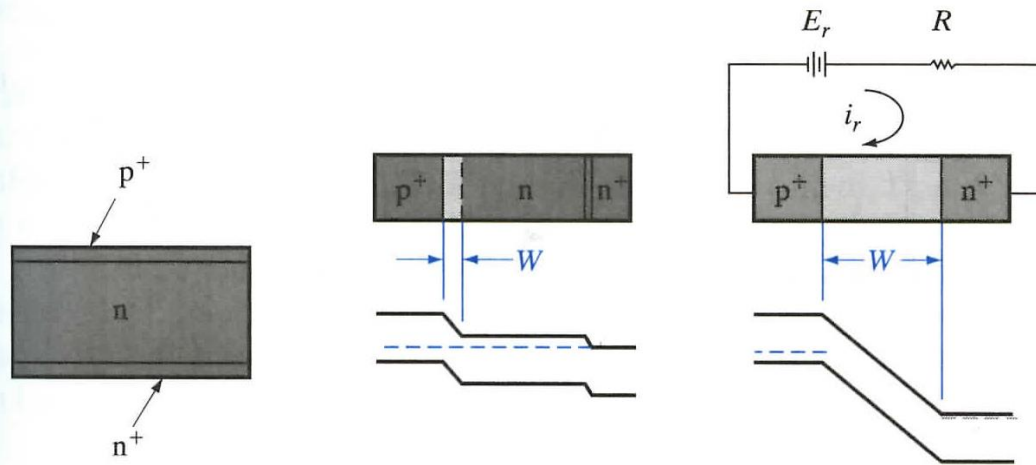
$$X_{no} = \frac{\epsilon E_{max}}{q N_d} = \left[\frac{2\epsilon (V_0 + V_r)}{q N_d} \right]^{1/2}$$

$$(V_0 + V_r) = \frac{\epsilon^2 E_{max}^2}{q^2 N_d^2} \cdot \frac{q N_d}{2\epsilon} = \frac{\epsilon E_{max}^2}{2q N_d} = E_{critical}^2$$



Neamen
Fig. 7-14

P-N Junction "Punch-Through"



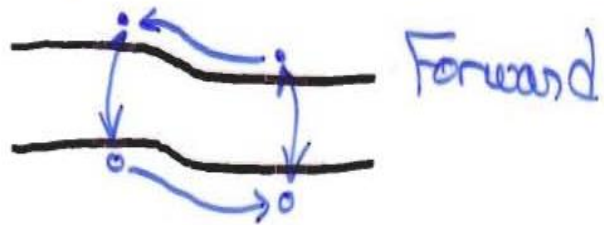
Depletion width expands across entire length L of n-region

→ Breakthrough occurs below V_{Br}

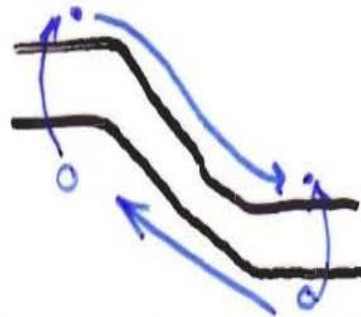
$$x_{n0} = \left[\frac{2\epsilon (V_0 + V_r)}{q N_d} \right]^{1/2} = L$$

▷ Recombination / Generation in Transition Region

We assumed $w \ll L_n, L_p$ so



Recombination in
Neutral Regions



Generation + Diffusion
of minority carriers to
transition regions.

Now consider Transition region processes
too for $W \sim L_n, L_p$

Forward

so recombination
takes place both outside
and inside W .

Free carriers available $\propto n_i$

Calculation shows:

$$I_{\text{transition}} \propto e^{qV/2kT} \quad \text{inside } W$$

recombination

trs. P_n and N_p , a.k.a.

plus increases as $e^{qV/kT}$ outside W .

$$I_{\text{total}} = I_{\text{recombination}}^{\text{neutral}} + I_{\text{recombination}}^{\text{inside } W, \text{ transition regions}}$$

$$= I_1 \left(e^{\frac{qV}{kT}} - 1 \right) + I_2 \left(e^{\frac{qV}{kT \cdot 2}} - 1 \right)$$

Outside
Inside

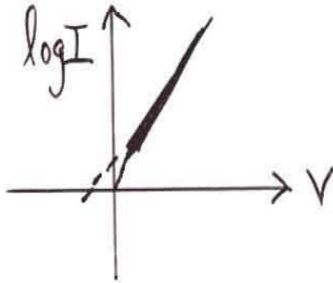
$$\approx I_0'$$

analogous to
diode equation

$n \equiv$ ideality factor

$n > 1$ represents departure from ideality

$$\text{Ratio: } \frac{I_{\text{neutral recombination}}}{I_{\text{transition recombination}}} \propto \frac{n_i^2 e^{qV/kT}}{n_i e^{qV/2kT}} \propto n_i e^{qV/2kT}$$

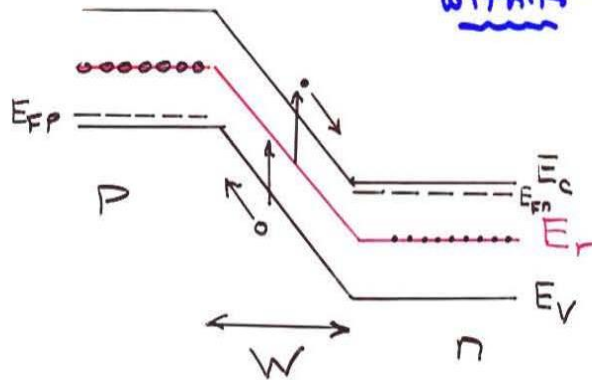


When ratio is small, n_i goes up.
 Ratio small for n_i small
 Ratio small for V small.



Reverse

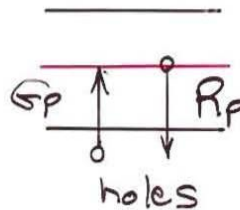
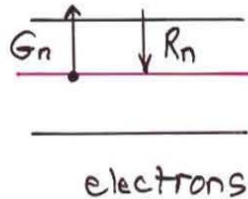
- Now generate carriers within W thermally.



Reverse: generation
Forward: recombination

Recombination

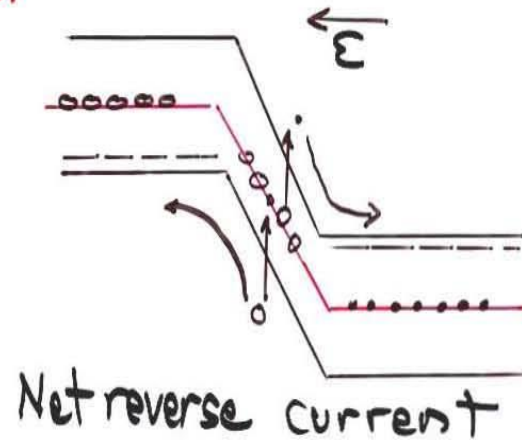
For $V=0$, generation and recombination balance.



For $V = V_{\text{reverse}}$, carriers swept out,
so recombination negligible.

Net result: generation $G_n \gg R_n$
 $G_p \gg R_p$
→ Net current flow.

Levels near mid-gap
most effective.



Why?

Minimum E required to excite both e^- and h^+

How to get?



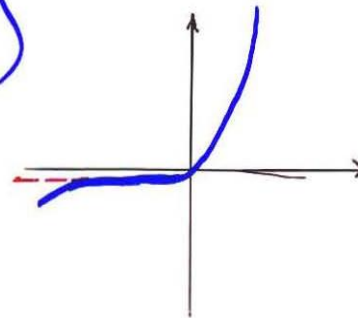
Also Ohio state research!

Generation increases with V_r .

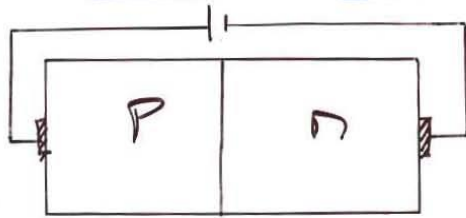
Why?



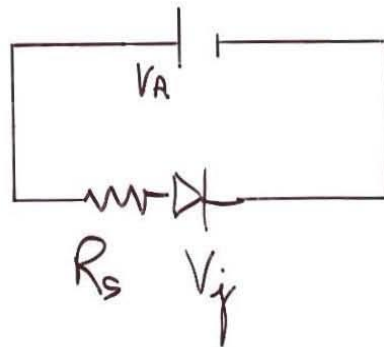
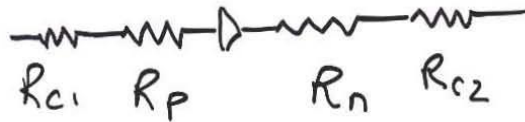
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Ohmic (or Contact) Losses



Can't neglect
resistance in neutral
region or external
contacts



R_c = contact resistance
(typically $10^{-5} - 10^{-6} \Omega \text{ cm}$)

$R =$

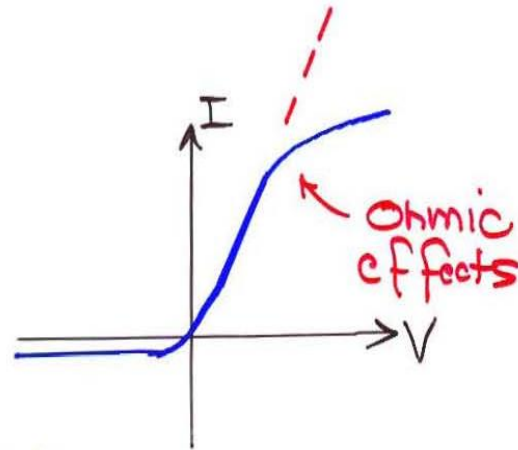


$$R_s = \text{series resistance} \\ = R_c + R_n + R_p$$

$$R_s = \text{series resistance} \\ = R_c + R_n + R_p$$

V_A = applied voltage

$$V_j = V_{\text{junction}} = V_A - IR_s$$



Added complication: $\sigma = ne\mu$

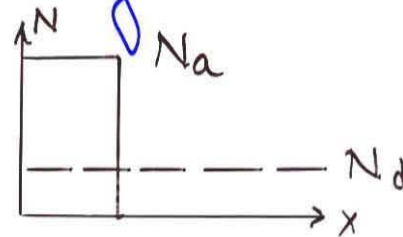
increases with higher voltage so R_n and R_p decrease
 $R_n(I), R_p(I)$

Avoid ohmic effects: Large A; operate device at I below non-ohmic range.

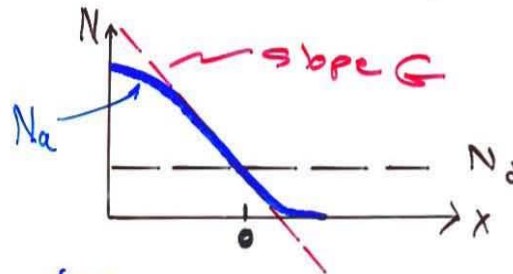
Graded Junctions

Contrast abrupt step junction (alloy, epi growth) with graded junction (diffused)

Recall abrupt:



Graded:



N profile spreads out

$$N_d - N_a = Gx$$

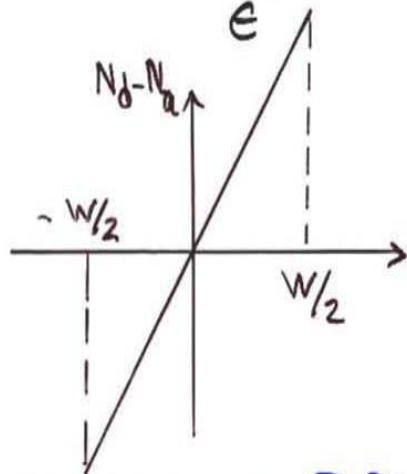
$G = \text{gradient}$

$$\frac{d\phi}{dx} = \frac{q}{\epsilon} (p - n + N_d^+ - N_a^-)$$

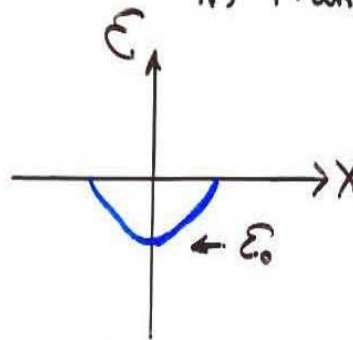
$$\approx \frac{q}{\epsilon} \phi x$$

assume $N_d = N_d^+$
 $N_a = N_a^-$

and $n \sim p \sim 0$
 in transition region



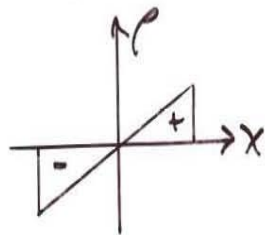
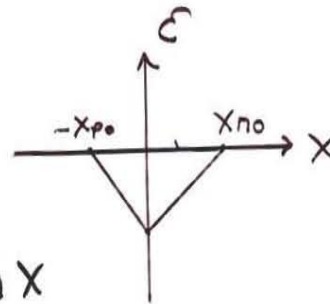
Net Impurity Profile



$\phi \propto x^2$ so Parabolic

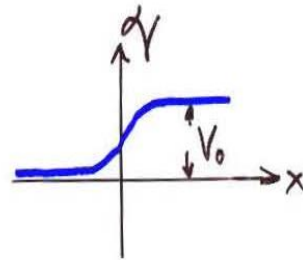
versus linear :

$$\begin{aligned}
 |Q| &= \int \rho A dx = qA \int_0^{w/2} Gx dx \\
 &= qA \frac{G}{2} x^2 \Big|_0^{w/2} \\
 &= qAG \frac{w^2}{8}
 \end{aligned}$$



charge greatest at edges of transition region

$$V = - \int \mathcal{E} dx \propto x$$



Most results derived
for abrupt junctions can also apply to
graded junctions (e.g., generation, recombination,
injection),
but some alterations in functional
form of equations.

so basic concepts still hold.